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**Quick Reference**

Search by part #

Check distributor part inventory

**Stock Check**

**Products**

Browse Heat sinks

- By Device -
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**Useful Links**

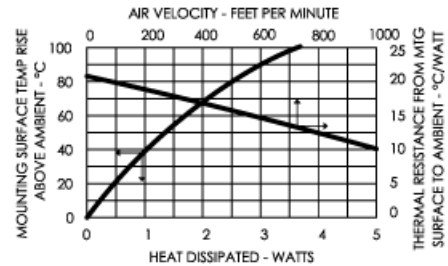
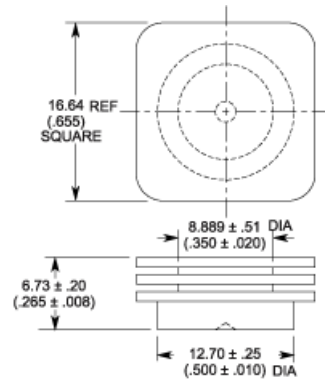
- [Building a part #](#)
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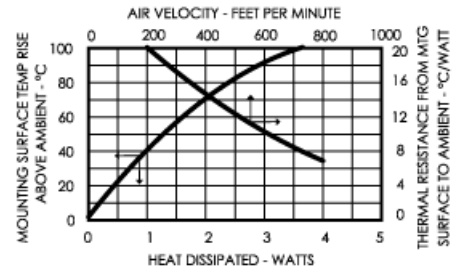
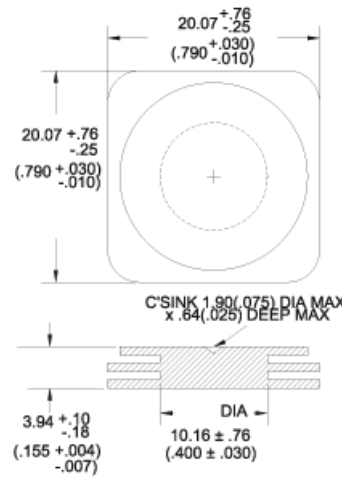
## Radial Fin Heat Sinks for Microprocessors

- Bond-on heat sinks for leadless chip carriers and flat packs.
- Primarily designed for 68-position devices.
- The 2283 is ideally suited to limited board space applications with high air flow.

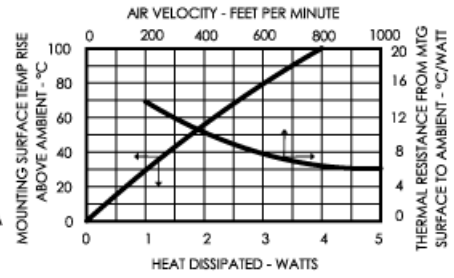
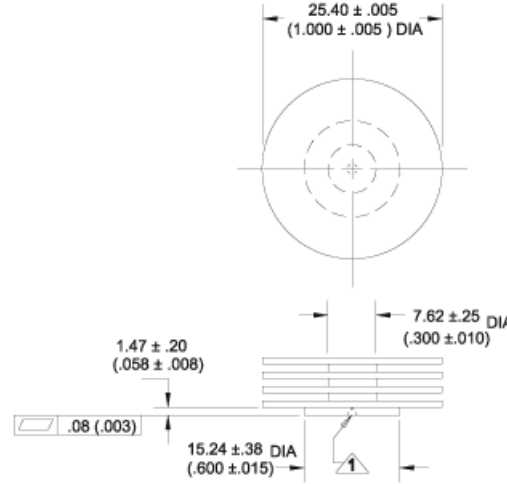
**Part Number: 2283BG**



**Part Number: 2286BG<**

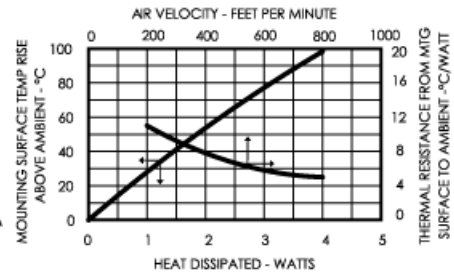
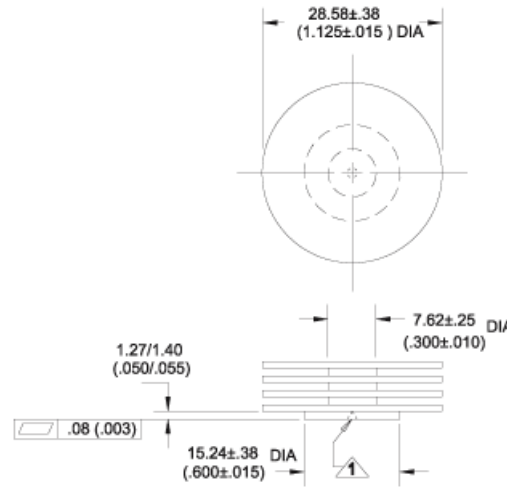


**Part Number: 2288BG**



**Part Number: 2292BG**

RoHS Compliant



**Part Number: 2296BG**



